Representative Email

**URL** for Additional Information

PART INFORMATION

Mfg Item Number

Mg Item Name

NI-880

SUPPLIER Company Name Freescale Semiconductor Inc Company Unique ID 14-141-7928 Response Date 2018-06-25 0419K10617D002A1.23 Response Document ID Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406

DECLARATION

EU RoHS
Pb Free
HalogenFree
Plating Indicator
EU RoHS Exemption(s)

eppanlst@freescale.com

www.freescale.com

MANUFACTURING Mfg Item Number MRF6S24140HR3 Mfg Item Name NI-880 Version ALL Weight 9.733700 UoM Unit Volume EACH J-STD-020 MSL Rating Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles 3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Co
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight
Exemplions	6(b): Lead as an alloying element in aluminium containing up to 0.4% lead by weight
	6(c): Copper alloy containing up to 4% lead by weight
	7(a): Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)
	7(b): Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications
	7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound
	7(c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher
	7(c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC
	7(c)-IV: Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors
	15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Cap/Cover	1.4456						g				
Cap/Cover		Metals	Aluminum Oxides (Al2O3)	1344-28-1		1.3646464	g	944000	94.4	140198	14.0198
Cap/Cover		Solvents, additives, and other materials	Calcium monoxide	1305-78-8		0.007228	g	5000	0.5	742	0.0742
Cap/Cover		Metals	Magnesium-oxide	1309-48-4		0.014456	g	10000	1	1485	0.1485
Cap/Cover		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.057824	g	40000	4	5940	0.594
Cap/Cover		Metals	Titanium (IV) Oxide	13463-67-7		0.0014456	g	1000	0.1	148	0.0148
Bonding Wire, Aluminum	0.0918						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0918	g	1000000	100	9431	0.9431
Silicon Semiconductor Die	0.0038						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000076	g	20000	2	7	0.0007
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.003724	g	980000	98	382	0.0382
Silicon Semiconductor Die	0.0038						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.000076	g	20000	2	7	0.0007
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.003724	g	980000	98	382	0.0382
Header Assembly	8.1849						g				
Header Assembly		Metals	Aluminum Oxides (Al2O3)	1344-28-1		0.27352299	g	33418	3.3418	28100	2.81
Header Assembly		Metals	Cobalt, metal	7440-48-4		0.0066134	g	808	0.0808	679	0.0679
Header Assembly		Metals	Copper, metal	7440-50-8		3.65233156	g	446228	44.6228	375225	37.5225
Header Assembly		Metals	Gold, metal	7440-57-5		0.11915577	g	14558	1.4558	12241	1.2241
Header Assembly		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00031921	g	39	0.0039	32	0.0032
Header Assembly		Solvents, additives, and other materials	Silicon	7440-21-3		0.00757103	g	925	0.0925	777	0.0777
Header Assembly		Metals	Iron, metal	7439-89-6		0.14524105	g	17745	1.7745	14921	1.4921
Header Assembly		Metals	Magnesium, metal	7439-95-4		0.00511556	g	625	0.0625	525	0.0525
Header Assembly		Metals	Manganese, metal	7439-96-5		0.00416611	g	509	0.0509	428	0.0428
Header Assembly		Metals	Molybdenum, metal	7439-98-7		3.72595474	g	455223	45.5223	382802	38.2802
Header Assembly		Nickel (external applications only)	Nickel	7440-02-0		0.18791712	g	22959	2.2959	19305	1.9305
Header Assembly		Metals	Silver, metal	7440-22-4		0.05699146	g	6963	0.6963	5855	0.5855
Silicon Semiconductor Die	0.0038						g				
Silicon Semiconductor Die		Metals	Gold, metal	7440-57-5		0.00003876	g	10200	1.02	3	0.0003
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.00007522	g	19796	1.9796	7	0.0007
Silicon Semiconductor Die		Glass	Silicon, doped			0.00368602	q	970004	97.0004	378	0.0378

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http://www.NXP.com/files/abstract/corporate/ehs\_epp/IPC-1752-2\_v1.1\_MCD\_Template.pdf

LINKS TO BLANK IPC1752 FORMS Blank IPC1752 v1.1 Form IPC1752 XML LINKS

http://www.freescale.com/mcds/MRF6S24140HR3\_IPC1752\_v11.xml

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